

PMP15012_LMR16020 Buck-boost				
Item #	Manufacturer	Quantity	Designator	Description
1	Texas Instruments	1	U2	Adjustable Precision Zener Shunt Regulator, 3-pin SOT-23
2	Texas Instruments	1	U1	SIMPLE SWITCHER, 60 V 2 A, 2.2 MHz Step-Down Converter with 40 μ A IQ, DDA0008E
3	Keystone	4	TP1, TP2, TP3, TP4	Terminal, Turret, TH, Double
4	Vishay-Dale	1	R19	RES, 100 k, 1%, 0.1 W, 0603
5	Vishay-Dale	1	R17	RES, 10.0 k, 1%, 0.1 W, 0603
6	Vishay-Dale	2	R15, R20	RES, DNP, 1%, 0.1 W, 0603
7	Yageo America	1	R14	RES, DNP ohm, 1%, 0.1W, 0603
8	Vishay-Dale	1	R13	RES, 2.00 k, 1%, 0.1 W, 0603
9	Yageo America	1	R12	RES, 2.49 k, 1%, 0.1 W, 0603
10	Vishay-Dale	1	R11	RES, 15.0 k, 1%, 0.1 W, 0603
11	Vishay-Dale	1	R7	RES, 49.9 ohm, 1%, 0.1W, 0603
12	Vishay-Dale	1	R6	RES, 15.8 k, 1%, 0.1 W, 0603
13	Vishay-Dale	1	R5	RES, 300 k, 1%, 0.1 W, 0603
14	Vishay-Dale	1	R3	RES, 49.9 k, 1%, 0.1 W, 0603
15	Vishay-Dale	1	R2	RES, 12.1 k, 1%, 0.1 W, 0603
16	Vishay-Dale	1	R1	RES, 31.6 k, 1%, 0.1 W, 0603
17	Diodes Inc.	1	Q1	Transistor, PNP, 40V, 0.2A, SOT-23
18	Würth Elektronik eiSos	1	L1	Inductor, Shielded Drum Core, Superflux, 5.5 μ H, 10 A, 0.0112 ohm, SMD
19	Diodes Inc.	1	D1	Diode, Schottky, 60V, 7A, PowerDI5
20	MuRata	1	C14	CAP, CERM, 0.1 μ F, 100 V, +/- 10%, X7R, 0603
21	MuRata	2	C12, C13	CAP, CERM, 0.22 μ F, 100 V, +/- 10%, X7R, 0805
22	TDK	2	C10, C11	CAP, CERM, 4.7 μ F, 100 V, +/- 10%, X7S, 1210
23	Panasonic	1	C9	CAP, AL, 56 μ F, 63 V, +/- 20%, 30 ohm, SMD
24	MuRata	1	C8	CAP, CERM, DNP, 25 V, +/- 10%, X7R, 0603
25	MuRata	1	C7	CAP, CERM, 1 μ F, 25 V, +/- 10%, X7R, 0805
26	Vishay-Sprague	1	C6	CAP, TA, 100 μ F, 20 V, +/- 10%, 0.15 ohm, SMD
27	Kemet	1	C5	CAP, CERM, DNP, 50 V, +/- 10%, X7R, 0603
28	MuRata	1	C4	CAP, CERM, 0.1 μ F, 16 V, +/- 10%, X7R, 0603
29	MuRata	2	C1, C2	CAP, CERM, 47 μ F, 25 V, +/- 20%, X5R, 1206_190

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